



TU-84P MF

Prepreg: TU-84P MF

TU-84P MF medium flow, halogen-free prepreg consist of optimal resin flow specially formulated for unique purpose bonding application. The special design TU-84P MF medium flow, halogen-free prepreg is appropriate for applying in multiple layer rigid-flex bonding, heat sink bonding and die cavity board application. TU-84P MF medium flow prepreg also provide excellent bonding performance with a variety of polyimide materials and with excellent high Tg, low CTE thermal performance for sequential lamination and lead-free processes.

Applications

- Rigid-flex
- Heat sink, Cavity

Performance and Processing Advantages

- Stable resin flow and resin filling capability
- Excellent bonding strength with polyimide materials
- Low resin powder dust generation
- Higher Tg and halogen free characteristics
- Lead Free process compatible
- Reduced Z-axis thermal expansion
- Superior dimensional stability, thickness uniformity and flatness
- Good drilling processability
- Excellent through-hole and soldering reliability
- Superior dielectric thickness control
- Compatible with AOI process with UV-block property

Industry Approvals

- IPC-4101 Type Designation : /127, /128, /130
- UL Designation – ANSI Grade: FR-4.1
- UL File Number: E189572
- Flammability Rating: 94V-0
- Maximum Operating Temperature: 130°C

Standard Availability

- Thickness: 0.002" [0.05mm] (106 type x 1 ply) to 0.003" [0.08mm] (1080 type x 1 ply)
- Prepregs: Available in roll or panel form
- Glass Styles: 106 and 1080, other prepreg grades are available upon request

